

WEST Search History

DATE: Wednesday, September 22, 2004

Hide? Set Name Query

Hit Count

DB=USPT; PLUR=YES; OP=ADJ

| | | | |
|--------------------------|----|--|-----|
| <input type="checkbox"/> | L3 | L1 and 134/\$.ccls. | 19 |
| <input type="checkbox"/> | L2 | L1 and 134/.ccls. | 0 |
| <input type="checkbox"/> | L1 | quartz with (metal or steel or aluminum) with wall | 651 |

END OF SEARCH HISTORY

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L5: Entry 10 of 11

File: USPT

May 26, 1992

DOCUMENT-IDENTIFIER: US 5115576 A

TITLE: Vapor device and method for drying articles such as semiconductor wafers with substances such as isopropyl alcohol

Current US Cross Reference Classification (1):
134/21

CLAIMS:

3. A device according to claim 1, where said vacuum process chamber includes a quartz liner.

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L3: Entry 1 of 19

File: USPT

Mar 16, 2004

DOCUMENT-IDENTIFIER: US 6706334 B1

TITLE: Processing method and apparatus for removing oxide film

Detailed Description Text (35):

The treatment vessel 110 is constituted of aluminum materials and its inner wall is provided with quartz (SiO.sub.2) linings 113 and 114 to be protected from metal pollution, erosion or the like. The treatment vessel 110 can be formed as a housing whose transverse plane may have various shapes such as a circle, a square and a polygon. A bottom plate 112 having a predetermined thickness is fixed to the bottom of the treatment vessel 110. A base 129 is disposed on the bottom plate 112, and a cylindrical susceptor 120 is provided on the base 129. The wafer W is placed on the top of the susceptor 120 and clamped by a quartz-made clamp ring 121. A jacket (or a pipe) 122 for holding a chiller and a heat exchanger 123 are included in the susceptor 120. The jacket 122 and heat exchanger 123 can be formed integrally as one component. The chiller is supplied from a chiller supply unit 142 into the jacket 122 through a cooling pipe 143 to cool the wafer W down to a given temperature, such as a temperature not higher than room temperature.

Current US Cross Reference Classification (1):134/1.1Current US Cross Reference Classification (2):134/1.2Current US Cross Reference Classification (3):134/3[Previous Doc](#)[Next Doc](#)[Go to Doc#](#)

[First Hit](#) [Previous Doc](#) [Next Doc](#) [Go to Doc#](#)**End of Result Set**☐ [Generate Collection](#) [Print](#)

L2: Entry 1 of 1

File: DWPI

Jan 28, 1998

DERWENT-ACC-NO: 1996-334173

DERWENT-WEEK: 200328

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TITLE: Wet chemical treatment installation for substrate plates - has lifting device with respective transport carriages for substrate plates and substrate plate holder

INVENTOR: DURST, J; SCHULZ, W ; SIGEL, H

PATENT-ASSIGNEE:

ASSIGNEE

CODE

STEAG MICROTECH GMBH DONAUESCHINGEN

STGG

STEAG MICROTECH GMBH

STGG

STEAGMICRO TECH GMBH

STGG

PRIORITY-DATA: 1995DE-1046990 (December 15, 1995), 1995DE-1000239 (January 5, 1995)

[Search Selected](#)[Search ALL](#)[Clear](#)

PATENT-FAMILY:

| PUB-NO | PUB-DATE | LANGUAGE | PAGES | MAIN-IPC |
|---|--------------------|----------|-------|-------------|
| <input type="checkbox"/> CN 1171858 A | January 28, 1998 | | 000 | H01L021/00 |
| <input type="checkbox"/> WO 9621241 A1 | July 11, 1996 | G | 045 | H01L021/00 |
| <input type="checkbox"/> DE 19546990 A1 | July 11, 1996 | | 021 | B65G049/04 |
| <input type="checkbox"/> DE 19546990 C2 | July 3, 1997 | | 018 | B65G049/04 |
| <input type="checkbox"/> DE 19549487 A1 | August 7, 1997 | | 045 | B65G049/04 |
| <input type="checkbox"/> FI 9702733 A | June 25, 1997 | | 000 | H01L000/00 |
| <input type="checkbox"/> DE 19549488 A1 | September 4, 1997 | | 000 | B65G049/04 |
| <input type="checkbox"/> DE 19549490 A1 | September 11, 1997 | | 001 | B65G049/04 |
| <input type="checkbox"/> EP 801814 A1 | October 22, 1997 | G | 000 | H01L021/00 |
| <input type="checkbox"/> JP 10503327 W | March 24, 1998 | | 040 | H01L021/304 |
| <input type="checkbox"/> KR 98701133 A | April 30, 1998 | | 000 | H01L021/00 |
| <input type="checkbox"/> US 5902402 A | May 11, 1999 | | 000 | B05C003/00 |
| <input type="checkbox"/> JP 3088463 B2 | September 18, 2000 | | 016 | H01L021/304 |

| | | | |
|--|-------------------|-------|------------|
| <input type="checkbox"/> <u>DE 19549487 C2</u> | November 16, 2000 | 000 | B65G049/04 |
| <input type="checkbox"/> <u>DE 19549490 C2</u> | January 18, 2001 | 000 | B65G049/04 |
| <input type="checkbox"/> <u>TW 399224 A</u> | July 21, 2000 | 000 | H01L021/00 |
| <input type="checkbox"/> <u>DE 19549488 C2</u> | August 2, 2001 | 000 | B65G049/04 |
| <input type="checkbox"/> <u>EP 801814 B1</u> | August 29, 2001 | G 000 | H01L021/00 |
| <input type="checkbox"/> <u>DE 59509568 G</u> | October 4, 2001 | 000 | H01L021/00 |
| <input type="checkbox"/> <u>KR 275166 B</u> | January 15, 2001 | 000 | H01L021/00 |

DESIGNATED-STATES: CA CN FI JP KR SG US AT BE CH DE DK ES FR GB GR IE
IT LU MC NL PT SE AT BE CH DE DK ES FR GB GR IE IT LI LU NL PT SE AT BE
CH DE DK ES FR GB GR IE IT LI LU NL PT SE

CITED-DOCUMENTS:EP 523836; FR 2586658 ; GB 2178594 ; US 5301700

APPLICATION-DATA:

| PUB-NO | APPL-DATE | APPL-NO | DESCRIPTOR |
|---------------|-------------------|--------------------|------------|
| CN 1171858A | December 29, 1995 | 1995CN-0197255 | |
| CN 1171858A | December 29, 1995 | 1995WO-EP05153 | |
| CN 1171858A | | WO 9621241 | Based on |
| WO 9621241A1 | December 29, 1995 | 1995WO-EP05153 | |
| DE 19546990A1 | December 15, 1995 | 1995DE-1046990 | |
| DE 19546990C2 | December 15, 1995 | 1995DE-1046990 | |
| DE 19549487A1 | December 15, 1995 | 1995DE-1046990 | Div ex |
| DE 19549487A1 | December 15, 1995 | 1995DE-1049487 | |
| DE 19549487A1 | | DE <u>19546990</u> | Div ex |
| FI 9702733A | December 29, 1995 | 1995WO-EP05153 | |
| FI 9702733A | June 25, 1997 | 1997FI-0002733 | |
| DE 19549488A1 | December 15, 1995 | 1995DE-1046990 | Div ex |
| DE 19549488A1 | December 15, 1995 | 1995DE-1049488 | |
| DE 19549488A1 | | DE <u>19546990</u> | Div ex |
| DE 19549490A1 | December 15, 1995 | 1995DE-1046990 | Div ex |
| DE 19549490A1 | December 15, 1995 | 1995DE-1049490 | |
| DE 19549490A1 | | DE <u>19546990</u> | Div ex |
| EP 801814A1 | December 29, 1995 | 1995EP-0943224 | |
| EP 801814A1 | December 29, 1995 | 1995WO-EP05153 | |
| EP 801814A1 | | WO 9621241 | Based on |
| JP 10503327W | December 29, 1995 | 1995WO-EP05153 | |
| JP 10503327W | December 29, 1995 | 1996JP-0520722 | |
| JP 10503327W | | WO 9621241 | Based on |
| KR 98701133A | December 29, 1995 | 1995WO-EP05153 | |
| KR 98701133A | July 1, 1997 | 1997KR-0704546 | |
| KR 98701133A | | WO 9621241 | Based on |
| US 5902402A | December 29, 1995 | 1995WO-EP05153 | |

| | | | |
|---------------|-------------------|--------------------|----------------|
| US 5902402A | July 3, 1997 | 1997US-0875408 | |
| US 5902402A | | WO 9621241 | Based on |
| JP 3088463B2 | December 29, 1995 | 1995WO-EP05153 | |
| JP 3088463B2 | December 29, 1995 | 1996JP-0520722 | |
| JP 3088463B2 | | JP 10503327 | Previous Publ. |
| JP 3088463B2 | | WO 9621241 | Based on |
| DE 19549487C2 | December 15, 1995 | 1995DE-1046990 | Div ex |
| DE 19549487C2 | December 15, 1995 | 1995DE-1049487 | |
| DE 19549487C2 | | DE <u>19546990</u> | Div ex |
| DE 19549490C2 | December 15, 1995 | 1995DE-1046990 | Div ex |
| DE 19549490C2 | December 15, 1995 | 1995DE-1049490 | |
| DE 19549490C2 | | DE <u>19546990</u> | Div ex |
| TW 399224A | January 5, 1996 | 1996TW-0100109 | |
| DE 19549488C2 | December 15, 1995 | 1995DE-1046990 | Div ex |
| DE 19549488C2 | December 15, 1995 | 1995DE-1049488 | |
| DE 19549488C2 | | DE <u>19546990</u> | Div ex |
| EP 801814B1 | December 29, 1995 | 1995EP-0943224 | |
| EP 801814B1 | December 29, 1995 | 1995WO-EP05153 | |
| EP 801814B1 | | WO 9621241 | Based on |
| DE 59509568G | December 29, 1995 | 1995DE-0509568 | |
| DE 59509568G | December 29, 1995 | 1995EP-0943224 | |
| DE 59509568G | December 29, 1995 | 1995WO-EP05153 | |
| DE 59509568G | | EP 801814 | Based on |
| DE 59509568G | | WO 9621241 | Based on |
| KR 275166B | December 29, 1995 | 1995WO-EP05153 | |
| KR 275166B | July 1, 1997 | 1997KR-0704546 | |
| KR 275166B | | KR 98701133 | Previous Publ. |
| KR 275166B | | WO 9621241 | Based on |

399224 A , DE 19549488 C2 INT-CL (IPC): B05C 3/00; B65G 49/04; B65G 49/07; H01L 0/00; H01L 21/00; H01L 21/30; H01L 21/304; H01L 21/306; H01L 21/68

ABSTRACTED-PUB-NO: EP 801814B

BASIC-ABSTRACT:

The installation (20) has a container (21) holding the treatment fluid (23) into which a holder (17) for the substrate plates (25) is lowered. Continuous lifting in and out of the substrate plate holder and the substrate plates relative to the treatment fluid is obtained via a lifting device with one transport carriage for the substrate plates and a second transport carriage for the holder.

The transport carriages for the substrate plates and the holder are coupled together via a linkage and displaced relative to a vertical guide rail, with the lifting drive acting on the first transport carriage.

USE - For uniform surface treatment of silicon wafers.
ABSTRACTED-PUB-NO:

US 5902402A
EQUIVALENT-ABSTRACTS:

The installation (20) has a container (21) holding the treatment fluid (23) into which a holder (17) for the substrate plates (25) is lowered. Continuous lifting in and out of the substrate plate holder and the substrate plates relative to the treatment fluid is obtained via a lifting device with one transport carriage for the substrate plates and a second transport carriage for the holder.

The transport carriages for the substrate plates and the holder are coupled together via a linkage and displaced relative to a vertical guide rail, with the lifting drive acting on the first transport carriage.

USE - For uniform surface treatment of silicon wafers.

The installation (20) has a container (21) holding the treatment fluid (23) into which a holder (17) for the substrate plates (25) is lowered. Continuous lifting in and out of the substrate plate holder and the substrate plates relative to the treatment fluid is obtained via a lifting device with one transport carriage for the substrate plates and a second transport carriage for the holder.

The transport carriages for the substrate plates and the holder are coupled together via a linkage and displaced relative to a vertical guide rail, with the lifting drive acting on the first transport carriage.

USE - For uniform surface treatment of silicon wafers.

WO 9621241A

CHOSEN-DRAWING: Dwg.3/16

TITLE-TERMS: WET CHEMICAL TREAT INSTALLATION SUBSTRATE PLATE LIFT
DEVICE RESPECTIVE TRANSPORT CARRIAGE SUBSTRATE PLATE SUBSTRATE PLATE
HOLD

DERWENT-CLASS: P42 Q35 U11

EPI-CODES: U11-C06A1B; U11-C07B;

SECONDARY-ACC-NO:
Non-CPI Secondary Accession Numbers: N1996-281583

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